

In semiconductor packaging, IC reliability depends not only on mold filling, but also on how the epoxy molding compound (EMC) evolves during transfer molding and curing. Digimat captures the material state from pre-cure to final cure, enabling engineers to:

- Model cure kinetics and glass transition (T_g)
- Capture cure shrinkage and residual stress
- Predict package warpage and die stress
- Evaluate delamination and reliability risks
- Connect transfer molding with structural CAE